

# FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16674

Generic Copy

Issue Date: 01-Jul-2011

<u>TITLE</u>: Final Notification for Wafer Fab Transfer of Small Signal Schottky (DSN2 0201 CSP) from ON Semiconductor ZR Fab in Phoenix (USA) to ON Semiconductor ISMF Fab in Seremban (Malaysia)

PROPOSED FIRST SHIP DATE: 01-Oct-2011

AFFECTED CHANGE CATEGORY(S): ON Semiconductor Fab Site

#### **FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor Sales Office or Masitah Aznam <a href="mailto:anam@onsemi.com">masitah.aznam@onsemi.com</a>

SAMPLES: Contact your local ON Semiconductor Sales Office

#### **ADDITIONAL RELIABILITY DATA: Available**

Contact your local ON Semiconductor Sales Office or Laura Rivers <a href="mailto:laura.rivers@onsemi.com">laura.rivers@onsemi.com</a>

#### **NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

## **DESCRIPTION AND PURPOSE:**

ON Semiconductor is notifying customers of its plan to transfer Small Signal Schottky in DSN2 0201 CSP package from ON Semiconductor ZR Fab in Phoenix (USA) to ON Semiconductor ISMF Fab in Seremban (Malaysia).

The ISMF facility is an ON Semiconductor owned wafer fab that has been producing products for ON Semiconductor since 1998. Several existing technologies within ON Semiconductor's product families are currently sourced from ISMF, including Zener, Diodes, Small Signal Transistor, and USB array filter products. ON Semiconductor Seremban Wafer FAB is an internal factory that is TS16949, ISO-9001 and ISO-14000 certified.

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## **RELIABILITY DATA SUMMARY:**

## **Reliability Test Results:**

<u>Package</u>: DSN2 0201 CSP <u>Qual Vehicle:</u> NSR02L30NXT5G

Test:	Conditions:	Interval:	Results
Autoclave+PC	Ta=121C RH=100% ~15 psig	96 hrs	0/240
TC+PC	Ta= -40C to 125 C	500 cyc	0/240
HTRB	Tj=150C,80% Rated Voltage	1008 hrs	0/240
IOL	Ta=25C, delta Tj=100C	7500 cyc	0/240
	Ton=Toff=2min		

## **ELECTRICAL CHARACTERISTIC SUMMARY:**

Available upon request

## **CHANGED PART IDENTIFICATION:**

Affected products from ON Semiconductor with date code 1140 representing WW40, 2011 and greater may be sourced from either the ISMF Fab in Seremban (Malaysia) or the ZR Fab in Phoenix (USA).

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# **List of affected General Parts:**

NSR02L30NXT5G NSR01L30NXT5G

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